

# CD74HC174, CD74HCT174

## High Speed CMOS Logic Hex D-Type Flip-Flop with Reset

### Features

- Buffered Positive Edge Triggered Clock
- Asynchronous Common Reset
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The Harris CD74HC174 and CD74HCT174 are edge triggered flip-flops which utilize silicon gate CMOS circuitry to implement D-type flip-flops. They possess low power and speeds comparable to low power Schottky TTL circuits. The devices contain six master-slave flip-flops with a common clock and common reset. Data on the D input having the specified setup and hold times is transferred to the Q output on the low to high transition of the CLOCK input. The MR input, when low, sets all outputs to a low state.

Each output can drive ten low power Schottky TTL equivalent loads. The CD74HCT174 is functional as well as, pin compatible to the 74LS174.

### Ordering Information

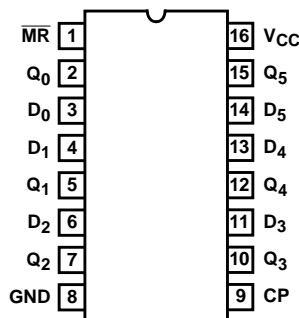
PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC174E	-55 to 125	16 Ld PDIP	E16.3
CD74HCT174E	-55 to 125	16 Ld PDIP	E16.3
CD74HC174M	-55 to 125	16 Ld SOIC	M16.15
CD74HCT174M	-55 to 125	16 Ld SOIC	M16.15
CD74HCT174W	-55 to 125	Wafer	

#### NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

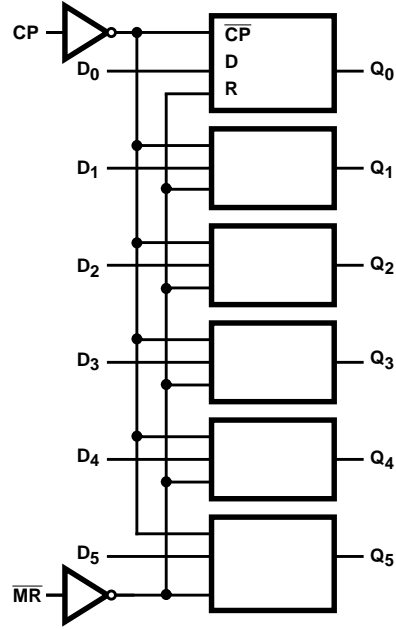
### Pinout

CD74HC174, CD74HCT174  
(PDIP, SOIC)  
TOP VIEW



CD74HC174, CD74HCT174

Functional Diagram

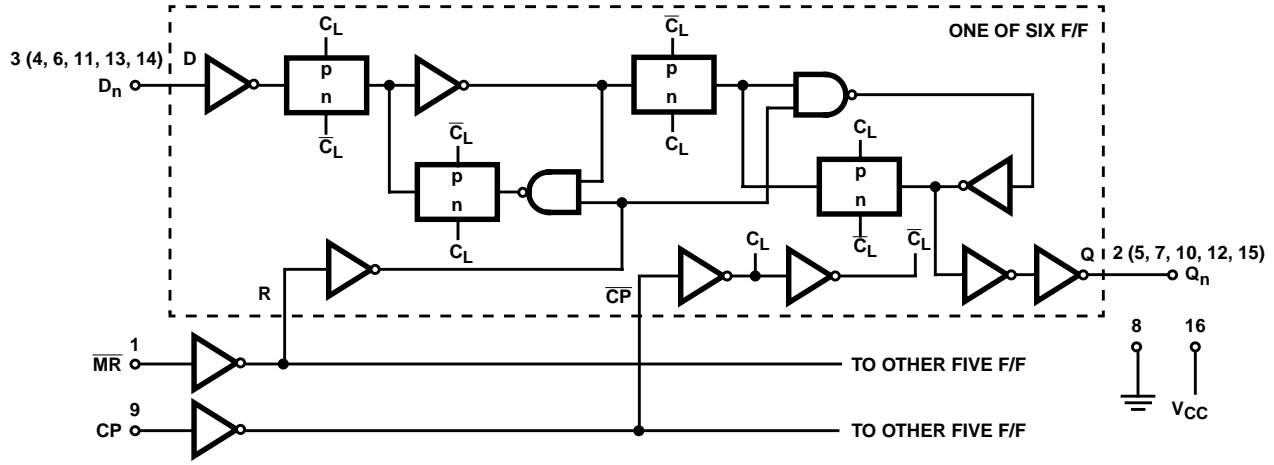


TRUTH TABLE

INPUTS			OUTPUT
RESET ( $\overline{MR}$ )	CLOCK CP	DATA $D_n$	$Q_n$
L	X	X	L
H	$\uparrow$	H	H
H	$\uparrow$	L	L
H	L	X	$Q_0$

NOTE: H = High Voltage Level, L = Low Voltage Level, X = Irrelevant,  $\uparrow$  = Transition from Low to High Level,  $Q_0$  = Level Before the Indicated Steady-State Input Conditions Were Established

Logic Diagram



# CD74HC174, CD74HCT174

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ .....	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package .....	85
SOIC Package .....	110
Maximum Junction Temperature .....	$150^{\circ}C$
Maximum Storage Temperature Range .....	$-65^{\circ}C$ to $150^{\circ}C$
Maximum Lead Temperature (Soldering 10s) .....	$300^{\circ}C$ (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range ( $T_A$ ) .....	$-55^{\circ}C$ to $125^{\circ}C$
Supply Voltage Range, $V_{CC}$	
HC Types .....	.2V to 6V
HCT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25°C			-40°C TO +85°C		-55°C TO 125°C		UNITS
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$
Quiescent Device Current	$I_{CC}$	$V_{CC}$ or GND	0	6	-	-	8	-	80	-	160	$\mu A$

## CD74HC174, CD74HCT174

### DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO +85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> to GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load (Note 4)	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

4. For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

### HCT Input Loading Table

INPUT	UNIT LOADS
CP	0.80
MR	0.55
D	0.15

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Specifications table, e.g. 360μA max at 25°C.

### Prerequisite For Switching Function

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>										
Clock Pulse Width	t <sub>w</sub>	-	2	80	-	100	-	120	-	ns
			4.5	16	-	20	-	24	-	ns
			6	14	-	17	-	20	-	ns
MR Pulse Width	t <sub>w</sub>	-	2	80	-	100	-	120	-	ns
			4.5	16	-	20	-	24	-	ns
			6	14	-	17	-	20	-	ns

## CD74HC174, CD74HCT174

### Prerequisite For Switching Function (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	MAX	MIN	MAX	MIN	MAX	
Setup Time, Data to Clock	t <sub>SU</sub>	-	2	60	-	75	-	90	-	ns
			4.5	12	-	15	-	18	-	ns
			6	10	-	13	-	15	-	ns
Hold Time, Data to Clock	t <sub>H</sub>	-	2	5	-	5	-	5	-	ns
			4.5	5	-	5	-	5	-	ns
			6	5	-	5	-	5	-	ns
Removal Time, $\overline{MR}$ to Clock	t <sub>REM</sub>	-	2	5	-	5	-	5	-	ns
			4.5	5	-	5	-	5	-	ns
			6	5	-	5	-	5	-	ns
Clock Frequency	f <sub>MAX</sub>	-	2	6	-	5	-	4	-	MHz
			4.5	30	-	24	-	20	-	MHz
			6	35	-	28	-	24	-	MHz

#### HCT TYPES

Clock Pulse Width	t <sub>w</sub>	-	4.5	20	-	25	-	30	-	ns
$\overline{MR}$ Pulse Width	t <sub>w</sub>	-	6	25	-	31	-	38	-	ns
Setup Time, Data to Clock	t <sub>SU</sub>	-	4.5	16	-	20	-	24	-	ns
Hold Time, Data to Clock	t <sub>H</sub>	-	6	5	-	5	-	5	-	ns
Removal Time, $\overline{MR}$ to Clock	t <sub>REM</sub>	-	4.5	12	-	15	-	18	-	ns
Clock Frequency	f <sub>MAX</sub>	-	6	25	-	20	-	17	-	MHz

### Switching Specifications Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
<b>HC TYPES</b>								
Propagation Delay, Clock to Q	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	165	205	250	ns
			4.5	-	33	41	50	ns
			6	-	28	35	43	ns
		C <sub>L</sub> = 15pF	5	13	-	-	-	ns
Propagation Delay, $\overline{MR}$ to Q	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	150	190	225	ns
			4.5	-	30	38	45	ns
			6	-	26	33	38	ns
		C <sub>L</sub> = 15pF	5	12	-	-	-	ns
Output Transition Times	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	75	95	110	ns
			4.5	-	15	19	22	ns
			6	-	13	16	19	ns
Input Capacitance	C <sub>IN</sub>	-	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 5, 6)	C <sub>PD</sub>	-	5	38	-	-	-	pF

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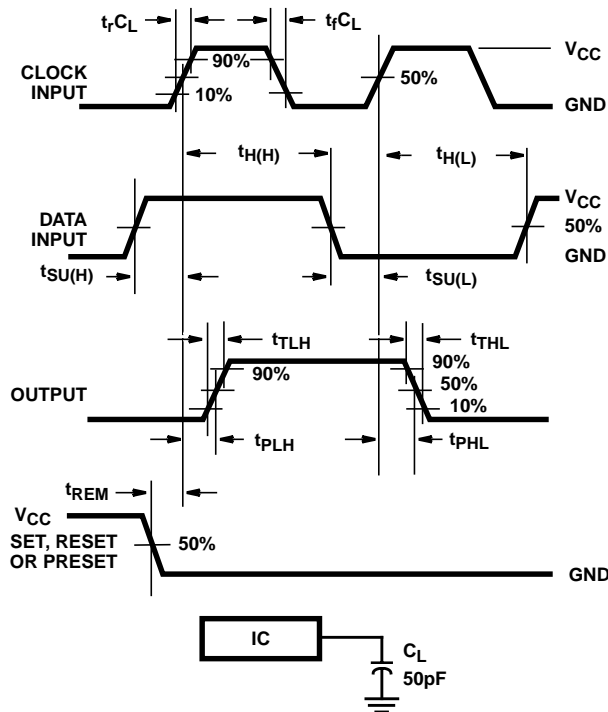
## Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
<b>HCT TYPES</b>								
Propagation Delay, Clock to Q	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	40	50	60	ns
			5	17	-	-	-	ns
Propagation Delay, $\overline{MR}$ to Q	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	44	55	66	ns
			5	18	-	-	-	ns
Output Transition Times	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	15	19	22	ns
Input Capacitance	$C_{IN}$	-	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 5, 6)	$C_{PD}$	-	5	44	-	-	-	pF

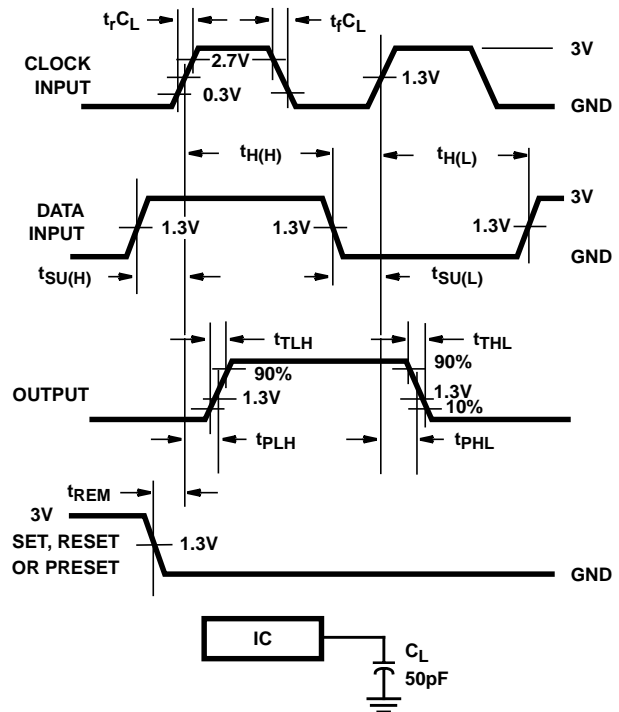
**NOTES:**

5.  $C_{PD}$  is used to determine the dynamic power consumption, per flip-flop.
6.  $P_D = V_{CC}^2 f_i + \sum (C_L V_{CC}^2 + f_O)$  where  $f_i$  = Input Frequency,  $f_O$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

## Test Circuits and Waveforms



**FIGURE 1. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS**



**FIGURE 2. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS**

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